

# PATENT ABSTRACTS OF JAPAN

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## (54) PROBE CARD

### (57)Abstract:

**PURPOSE:** To perform inspection even if the dimension of an electrode pad of a semiconductor device is small and the interval is narrow by forming plural conductive wirings on the surface of a probe card substrate and forming the tip part of these wirings in a cantilever-like contact which has been separated from the substrate surface.

**CONSTITUTION:** A contact 13 is a contact which has been formed in the tip part of each conductive wiring 12, floated from the surface of a probe card substrate 11 like a cantilever, and at the extreme tip, a contact part 13a projected downward is formed. Also, each conductive wiring 12 containing the contact 13 can be formed with high accuracy and minutely on the probe card substrate 11 by a process of a thin film formation, a lithography, etc. In this state, a probe card executes an inspection by allowing each corresponding contact 13 to come into contact onto each electrode pad 6 of a semiconductor device 5 which has been formed in a wafer 4 and inputting and outputting an electric signal. In such a way, even in case of the semiconductor device in which the dimension of the electrode pad is small and its interval is narrow, the contact is brought into contact with the electrode pad with high accuracy, and the inspection can be performed.

